Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.014”**

**.014”**

**ANODE**

**.006”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .006” min**

**Backside Potential: Cathode**

**APPROVED BY: DK DIE SIZE .014” X .014” DATE: 11/1/21**

**MFG: MOTOROLA THICKNESS .008” P/N: 1N4148**

**DG 10.1.2**

#### Rev B, 7/19/02